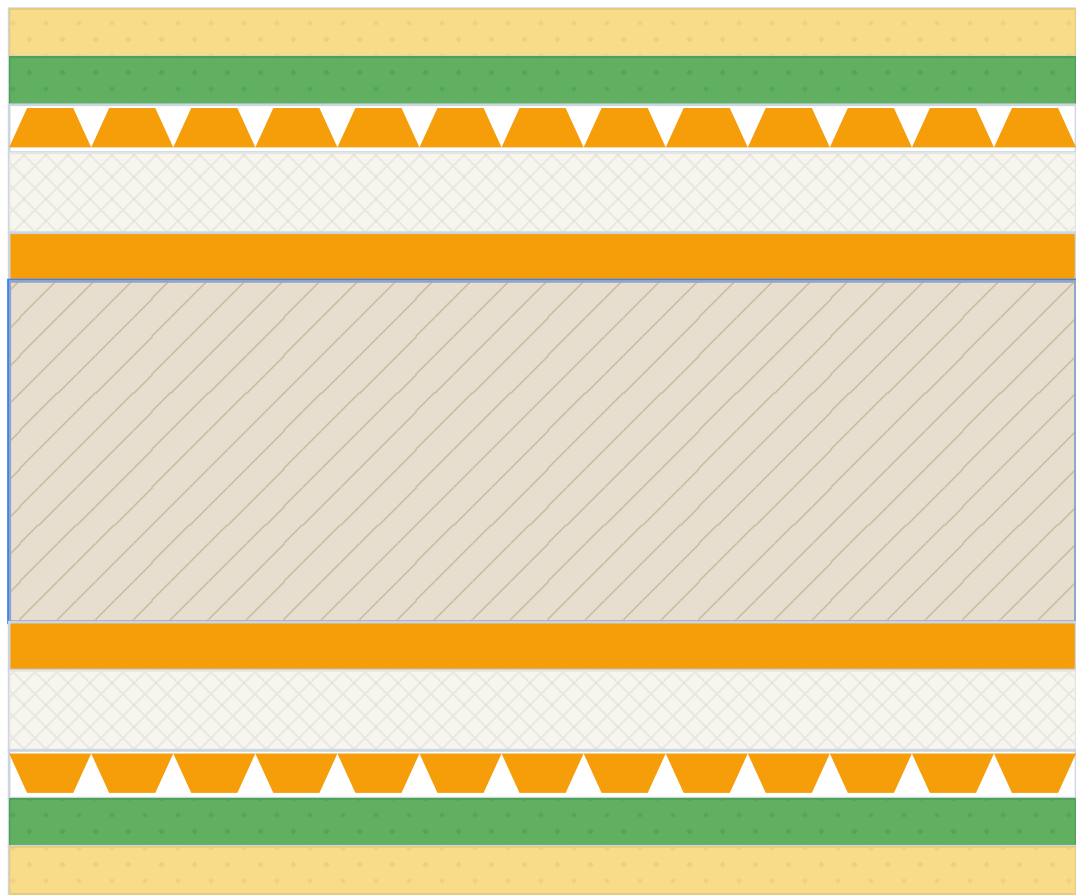


Top Surface Finish  
 Top Solder Mask  
**L1**  
 Prepreg  
**L2**  
 Core  
**L3**  
 Prepreg  
**L4**  
 Bottom Solder Mask  
 Bottom Surface Finish



**4L-1.6-7628-1-1-70**

| Spec       | Type    | Base Thickness | Processed Thickness | RC  | DK  |
|------------|---------|----------------|---------------------|-----|-----|
| ENIG       |         | 0.005          |                     |     |     |
|            |         | 0.020          |                     |     |     |
|            | Signal  | 0.018          | 0.018               |     |     |
| FR4 · 7628 | Prepreg | 0.196          | 0.1885              | 43% | 4.7 |
|            | Plane   | 0.035          | 0.035               |     |     |
| FR4        | Core    | 1.03           | 1.03                |     | 4.6 |
|            | Plane   | 0.035          | 0.035               |     |     |
| FR4 · 7628 | Prepreg | 0.196          | 0.1855              | 43% | 4.7 |
|            | Signal  | 0.018          | 0.018               |     |     |
|            |         | 0.020          |                     |     |     |
| ENIG       |         | 0.005          |                     |     |     |

Thickness After Lamination: 1.51 mm  
 Finished PCB Thickness: 1.56 mm ±10%  
 Inner layer Residual copper ratio: 70%